

REMARKS

Applicant thanks the Examiner for indicating that claim 22 is allowed and that claim 23 includes allowable subject matter.

Claims 21, 28 and 31-37 were rejected as anticipated by U.S. Patent No. 6,476,491 (Harada et al.).

Independent claims 21 and 34 have been amended to recite that the upper layer wiring and the lower layer wiring are arranged under a pad portion and in areas other than under the pad portion.

For example, in the particular embodiment illustrated in FIG. 13, the device includes lower layer wiring 59, 57 and upper layer wiring 61. The upper and lower layer wirings are present both under the pad portion and in areas other than under the pad portion. The upper and lower wirings are connected through a via hole 60 at an area that is not under the pad portion.

As explained in the pending specification (*see* page 24, lines 10-16; *see also* page 3, lines 9-15), forming the wirings under the pad portion, even though they are not connected there by vias, can alleviate problems relating to differences at the surface of a bump electrode formed on the pad portion.

FIG. 1 of the Harada et al. patent shows a multilayer wiring that includes a lower layer wiring 21 and an and upper layer wiring 25. An interlayer insulating film 22 covers the lower layer wiring. A via hole 24 (or 23) connects the lower layer wiring to the upper layer wiring.

However, in contrast to pending claims 21 and 34, only one of the metal wiring films 21, 25 in the Harada patent is present under the area defining the pad region (*see* 26 in FIG. 1). In particular, the lower metal wiring film 21 is not present under the pad electrode. Nor is there any suggestion of providing the metal wiring film 21 under the pad electrode.

At least for the foregoing reasons, applicant respectfully requests reconsideration and withdrawal of the rejections of claims 21, 28 and 31-37.

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Enclosed is a check for the Petition for Extension of Time fee. Please apply any other charges or credits to deposit account 06-1050.

Respectfully submitted,

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